

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (currently amended) A slurry for chemical mechanical polishing, which comprises a silica polishing material, an oxidizing agent, a benzotriazole-based compound, a diketone and water, and

wherein said diketone is at least one type of a compound selected from the group consisting of 1, 2-diketones, 1, 3-diketones and 1, 4-diketones.

2. (cancelled)

3. (currently amended) ~~A slurry for chemical mechanical polishing according to Claim 1~~ A slurry for chemical mechanical polishing, which comprises a silica polishing material, an oxidizing agent, a benzotriazole-based compound, a diketone and water, and

wherein a content weight ratio of said diketone to said benzotriazole-based compound (diketone / benzotriazole-based compound) is not less than 0.05 but not greater than 50.

4. (original) A slurry for chemical mechanical polishing according to Claim 1, wherein a value of a pH is in a range of 1 to 7.

5. (original) A slurry for chemical mechanical polishing according to Claim 1, wherein said silica polishing material is colloidal silica.

6. (new) The slurry for chemical mechanical polishing according to claim 1, wherein a content weight ratio of said diketone to said benzotriazole-based compound (diketone/benzotriazole-based compound) is not less than 0.05 but not greater than 50.